

**In the Specification:**

Please amend the specification as set forth below:

*Please amend the paragraph at page 1, lines 24-33, as set forth below:*

Since in the above technologies, a plurality of protuberant bumps (electrodes) are formed on a front surfaces of the substrates of semiconductor chips and the substrates are bonded to each other through the protuberant bumps (electrodes), the protuberant bumps (electrodes) must be made uniform in height. To realize this, grinding is generally used. However, when the bumps (electrodes) are ground, burrs are produced if the bumps (electrodes) are made of a sticky metal such as gold, thereby causing a problem that a short circuit occurs between adjacent bumps (electrodes).

*Please amend the paragraph at page 2, lines 21-25, as set forth below:*

It is an object of the present invention to provide a processing machine capable of easily making a plurality of electrodes projecting from the front surface of a plate-like workpiece uniform in height, without causing a short circuit ~~occurs to occur~~ between adjacent electrodes.